

RU1H35R-VB Datasheet N-Channel 100-V (D-S) MOSFET

PRODUCT	SUMMARY	
V _{(BR)DSS} (V)	r _{DS(on)} (Ω)	I _D (A)
100	0.017 at V _{GS} = 10 V	70 ^a

FEATURES

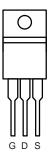
- TrenchFET[®] Power MOSFET
- 175 °C Junction Temperature
- Low Thermal Resistance Package
- 100 % R_g Tested

APPLICATIONS

D

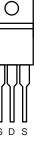
Isolated DC/DC Converters





Top View

TO-220AB



GC

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _C = 25 °C, unless oth	erwise noted		
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	100	V
Gate-Source Voltage		V _{GS}	± 20	v
Continuous Drain Current (T _J = 175 °C)	T _C = 25 °C	1-	70 ^a	
Continuous Drain Current (1j = 175°C)	T _C = 125 °C	I _D	35 ^a	A
Pulsed Drain Current		I _{DM}	145	
Avalanche Current	L = 0.1 mH	I _{AS}	31	
Single Pulse Avalanche Energy ^b	L = 0.11111	E _{AS}	60	mJ
	T _C = 25 °C	P	355 ^c	w
Maximum Power Dissipation ^b	T _A = 25 °C ^d	- P _D -	3.35	vv
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C

THERMAL RESISTANCE	RATINGS			
Parameter		Symbol	Limit	Unit
Junction-to-Ambient	PCB Mount	R _{thJA}	40	°C/W
Junction-to-Case (Drain)		R _{thJC}	0.4	C/W

Notes:

- a. Package limited.
- b. Duty cycle \leq 1 %.
- c. See SOA curve for voltage derating.

d. When Mounted on 1" square PCB (FR-4 material).

SPECIFICATIONS $T_J = 25 °$	C, unless o	therwise noted					
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{DS} = 0 V, I_{D} = 250 \mu A$	100			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2		4	v	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			50	μA	
		$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 \text{ °C}$			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 V$, $V_{GS} = 10 V$	120			А	
		V _{GS} = 10 V, I _D = 30 A		0.017		Ω	
Drain-Source On-State Resistance ^a	r _{DS(on)}	V_{GS} = 10 V, I _D = 30 A, T _J = 125 °C		0.023			
		V_{GS} = 10 V, I _D = 30 A, T _J = 175 °C		0.037			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A	25			S	
Dynamic ^b	•						
Input Capacitance	C _{iss}			1800		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		210			
Reverse Transfer Capacitance	C _{rss}			110			
Total Gate Charge ^c	Qg			90			
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 58 \text{ A}$		23		nC	
Gate-Drain Charge ^c	Q _{gd}			34			
Gate Resistance	Rg		0.5	1.3	3.1	Ω	
Turn-On Delay Time ^c	t _{d(on)}			24	35		
Rise Time ^c	t _r	$\label{eq:VDD} \begin{array}{l} V_{DD} = 100 \; V, \; R_{L} = 1.5 \; \Omega \\ I_{D} \cong 58 \; A, \; V_{GEN} = 10 \; V, \; R_{g} = 2.5 \end{array}$		220	330		
Turn-Off Delay Time ^c	t _{d(off)}			45	70	ns	
Fall Time ^c	t _f	Ω		200	300		
Source-Drain Diode Ratings and Ch	aracteristics 7	$\Gamma_{\rm C} = 25 \ ^{\circ}{\rm C}^{\rm b}$					
Continuous Current	ا _S				70	٨	
Pulsed Current	I _{SM}			115		A	
Forward Voltage ^a	V _{SD}	$I_{F} = 58 \text{ A}, V_{GS} = 0 \text{ V}$		1.0	1.5	V	
Reverse Recovery Time	t _{rr}			130	200	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 30 A, di/dt = 100 A/μs		8	12	А	
Reverse Recovery Charge	Q _{rr}			0.52	1.2	μC	

Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

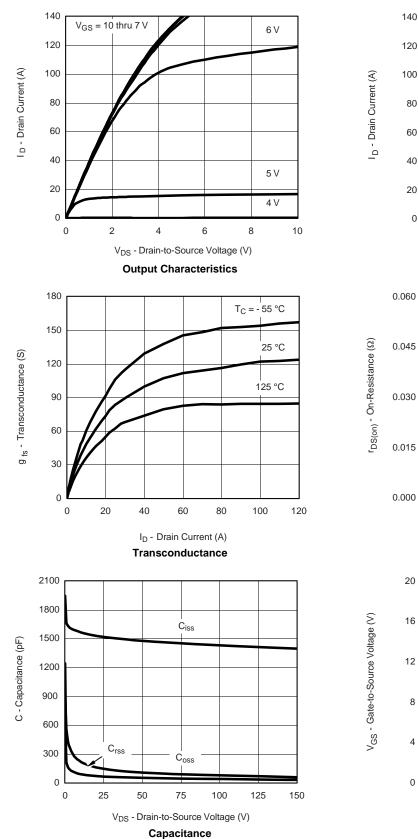
b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

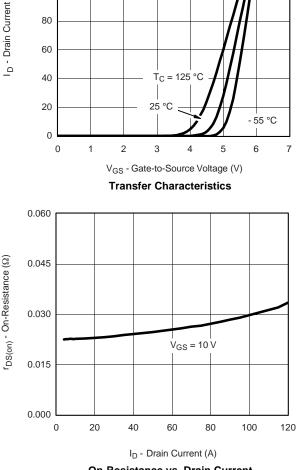
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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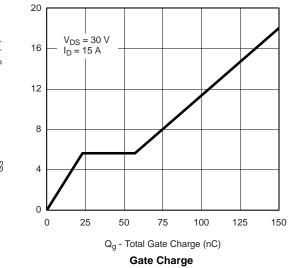




TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

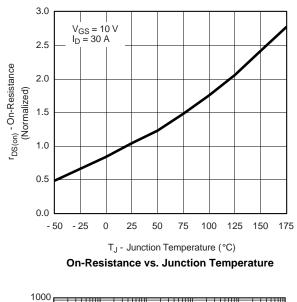


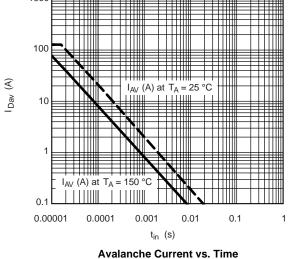
On-Resistance vs. Drain Current

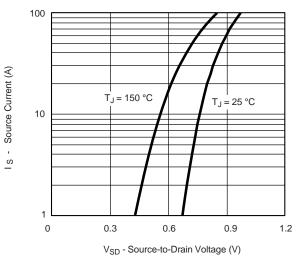




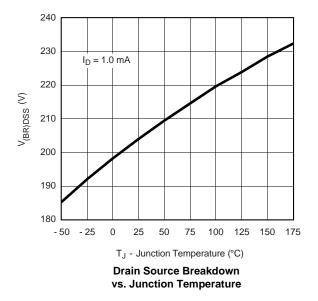
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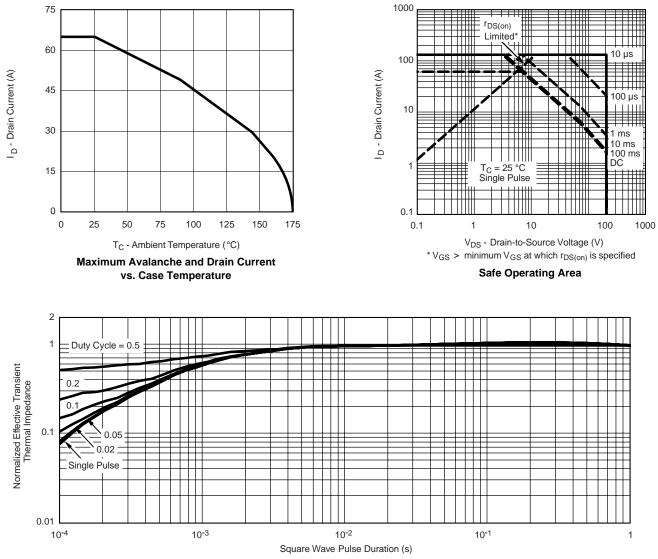


Source-Drain Diode Forward Voltage





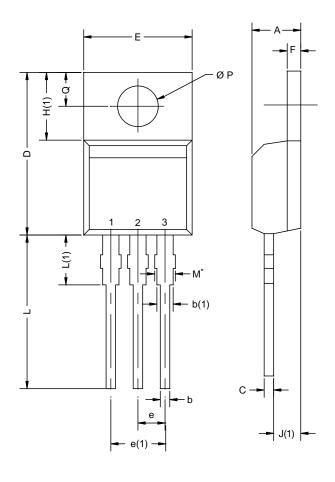
THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



TO-220AB



DIM.	MILLIN	MILLIMETERS		HES
	MIN.	MAX.	MIN.	MAX.
А	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
С	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
Е	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØΡ	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118

Notes

* M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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